

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1. (Original) An image sensor package comprising:
a transparent substrate comprising a base surface and a pocket sidewall;
a trace coupled to said base surface;
an image sensor comprising a first surface comprising an active area and a bond pad; and
a bump coupling said bond pad to said trace, wherein said image sensor is located within an image sensor pocket of said transparent substrate defined by said base surface and said pocket sidewall.
2. (Original) The image sensor package of Claim 1 wherein said transparent substrate further comprises a rear surface, said pocket sidewall extending between said base surface and said rear surface, wherein said trace extends from said base surface, along said pocket sidewall, and to said rear surface.
3. (Original) The image sensor package of Claim 2 wherein said trace comprises:
a first portion extending along said base surface to said pocket sidewall;
a second portion extending along said pocket sidewall from said base surface to said rear surface; and
a third portion extending along said rear surface.
4. (Original) The image sensor package of Claim 3 wherein said first portion, said second portion, and said third portion are integral.

5. (Original) The image sensor package of Claim 3 further comprising an interconnection ball coupled to said third portion.

6. (Original) The image sensor package of Claim 3 further comprising a pad coupled to said third portion.

7. (Original) The image sensor package of Claim 2 wherein said image sensor is entirely within said image sensor pocket.

8. (Original) The image sensor package of Claim 7 wherein said image sensor comprises a second surface below said rear surface of said transparent substrate.

9. (Original) The image sensor package of Claim 2 wherein said image sensor comprises a second surface coplanar with said rear surface of said transparent substrate.

10. (Original) The image sensor package of Claim 2 wherein said image sensor comprises a second surface above said rear surface of said transparent substrate.

11. (Original) The image sensor package of Claim 1 further comprising a bead forming a seal between a periphery of said image sensor and said base surface.

12. (Original) The image sensor package of Claim 11 wherein said image sensor, said bead, and said base surface define a cavity, said active area being located within said cavity.

13. (Original) The image sensor package of Claim 1 further comprising an underfill filling a region between said first surface of said image sensor and said base surface.

14. (Original) The image sensor package of Claim 13 wherein said underfill contacts and protects said active area.

15. (Original) An image sensor package comprising:
a transparent substrate comprising a rear surface and a front surface;
a rear trace coupled to said rear surface;
a front trace coupled to said front surface;
a via extending from said rear surface to said front surface and electrically coupling said rear trace to said front trace;

an image sensor comprising a first surface comprising an active area and a bond pad;

a bump coupling said bond pad to said rear trace;

a bead forming a seal between a periphery of said image sensor and said rear surface; and

a package body enclosing said bead and a side of said image sensor.

16-20. (Canceled)